PK562 (v1.1) October 12, 2012

100% Material Declaration Data Sheet for 7 Series FF901

Average Weight: 10.2338g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					**0.446519**	**4.363**
	Silicon (Si)	7440-21-3	100.00	Basis	0.446519	
Solder Bump					**0.029370**	**0.287**
	Tin (Sn)	7440-31-5	63.00	Basis	0.018503	
	Lead (Pb)	7439-92-1	37.00	Basis	0.010867	
Solder Paste					**0.071000**	**0.694**
	Tin (Sn)	7440-31-5	96.50	Basis	0.068515	
	Silver (Ag)	7440-22-4	3.00	Basis	0.002130	
	Copper (Cu)	7440-50-8	0.50	Basis	0.000355	
Capacitor 1					**0.037800**	**0.369**
	BaTiO3 type	12047-27-7	70.60	Ceramic	0.026687	
	Nickel (Ni)	7440-02-0	6.70	Inner electrode	0.002533	
	Copper (Cu)	7440-50-8	20.10	Outer electrode	0.007598	
	Nickel (Ni)	7440-02-0	0.80	Plating 1	0.000302	
	Tin (Sn)	7440-31-5	1.80	Plating 2	0.000680	
Capacitor 2					**0.007360**	**0.072**
	BaTiO3 type	12047-27-7	51.10	Ceramic	0.003761	
	Nickel (Ni)	7440-02-0	27.00	Inner electrode	0.001987	
	Copper (Cu)	7440-50-8	16.00	Outer electrode	0.001178	
	Glass	65997-17-3	0.900		0.000066	
	Nickel (Ni)	7440-02-0	2.00	Plating 1	0.000147	
	Tin (Sn)	7440-31-5	3.00	Plating 2	0.000221	
Capacitor 3					**0.004200**	**0.041**
	BaTiO3 type	12047-27-7	66.00	Ceramic	0.002772	
	Nickel (Ni)	7440-02-0	2.67	Inner electrode	0.000112	
	Copper (Cu)	7440-50-8	23.33	Outer electrode	0.000980	
	Nickel (Ni)	7440-02-0	2.33	Plating 1	0.000098	
	Tin (Sn)	7440-31-5	5.67	Plating 2	0.000238	

© Copyright 2012 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Underfill					**0.053000**	**0.518**
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	Basis	0.010600	
	Phenolic Resin	Trade Secret	15.00	Basis	0.007950	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	Basis	0.002650	
	Amine type accelerator	Trade Secret	5.00	Basis	0.002650	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.027295	
	Carbon Black	1333-86-4	1.00	Basis	0.000530	
	Additives	Trade Secret	2.50	Additive	0.001325	
Lid					**5.818000**	**56.851**
	Copper (Cu)	7440-50-8	99.12	Main Material	5.766802	
	Nickel (Ni)	7440-02-0	0.88	Main Material	0.051198	
Lid Adhesive					**0.103000**	**1.006**
	Aluminum Oxide Al203	1344-28-1	70.00	Basis	0.072100	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	30.00	Basis	0.030900	
Solder Ball					**0.856618**	**8.370**
	Tin (Sn)	7440-31-5	63.00	Main Material	0.539669	
	Lead (Pb)	7439-92-1	37.00	Main Material	0.316949	
Substrate					**2.806923**	**27.428**
	Copper (Cu)	7440-50-8	41.02		1.151484	
	Tin (Sn)	7440-31-5	0.83		0.023354	
	Lead (Pb)	7439-92-1	0.17		0.004856	
	Silver (Ag)	7440-22-4	0.02		0.000477	
	BT Core	N/A	44.06		1.236702	
	ABF	N/A	11.60		0.325659	
	Solder Mask	N/A	2.29		0.064391	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/05/2012	1.0	Initial Xilinx release.
10/12/2012	1.1	Update Substrate components.

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.